

REMARKS

Claims 1 - 8, 12 and 14 – 34 are pending in the present application, of which claims 15 – 34 have been withdrawn from consideration. By this Amendment, new Figure 53 has been added. New Figure 53 shows that a sidewall insulation film 32 is formed on the inter-layer insulation film 28 for the contact hole 30 in order to exemplify the feature of the present invention concerning a sidewall insulation film surrounding the contact hole, as called for in claim 2.

It is respectfully submitted that the subject matter illustrated in new Figure 53 is clearly supported by the specification as originally filed and therefore does not constitute new matter. More specifically, the bridging paragraph between pages 38 and 39 of the original specification clearly sets forth that the sidewall insulation film 32 is formed on the side walls of the inter-layer insulation film 28. As such, it is respectfully submitted that the Preliminary Amendment be entered in its entirety.

Applicant submits that the claims are in condition for allowance.

Applicant requests such action at an early date. If the Examiner believes that this application is not now in condition for allowance, the Examiner is requested to contact Applicant's undersigned attorney to arrange for an interview to expedite the disposition of this case.

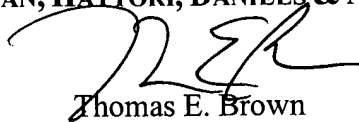
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If this paper is not timely filed, Applicant respectfully petitions for an appropriate extension of time. The fees for such an extension or any other fees that may be due with respect to this paper may be charged to Deposit Account No. 50-2866.

Respectfully submitted,

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Enclosure: New Drawing FIG. 53

AMENDMENTS TO THE DRAWINGS:

The attached sheet of drawing FIG. 53 is a cross-sectional view along the extending direction of the conductor patterns of the semiconductor device according to the second embodiment of the present invention, which shows a structure thereof.